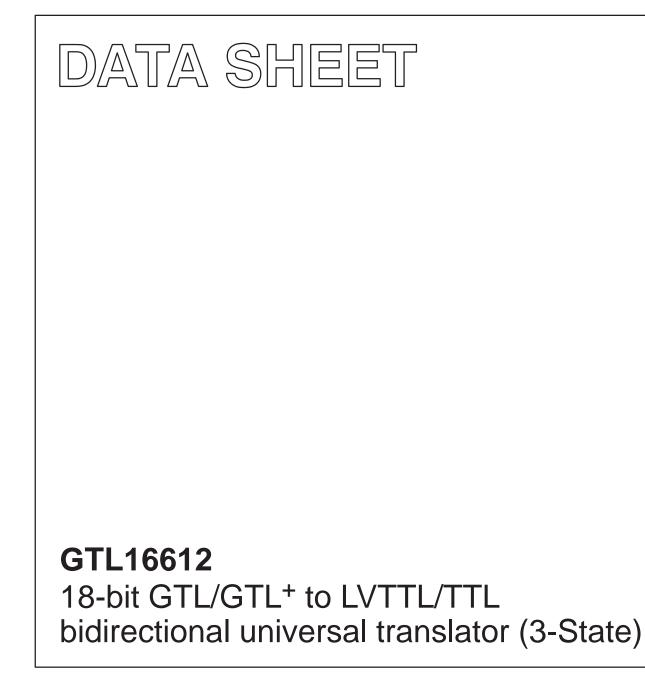
INTEGRATED CIRCUITS



Product specification Supersedes data of 1999 Sep 13 2000 Jun 19



GTL16612

FEATURES

- 18-bit bidirectional bus interface
- Translates between GTL/GTL+ logic levels (B ports) and LVTTL/TTL logic levels (A ports)
- 5 V I/O tolerant on the LVTTL/TTL side (A ports)
- No bus current loading when LVTTL/TTL output is tied to 5 V bus
- 3-State buffers
- Output capability: +64 mA/-32 mA on the LVTTL/TTL side (A ports); +40 mA on the GTL/GTL+ side (B ports)
- TTL input levels on control pins
- Power-up reset
- Power-up 3-State
- Positive edge triggered clock inputs
- Latch-up protection exceeds 500 mA per JESD78
- ESD protection exceeds 2000 V HBM per JESD22-A114, 200 V MM per JESD22-A115 and 1000 V CDM per JESD22-C101

QUICK REFERENCE DATA

DESCRIPTION

The GTL16612 is a high-performance BiCMOS product designed for V_{CC} operation at 3.3 V with I/O compatibility up to 5 V.

This device is an 18-bit universal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. Data flow in each direction is controlled by output enable (OEAB and OEBA), latch enable (LEAB and LEBA), and clock (CPAB and CPBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is High. When LEAB is Low, the A data is latched if CPAB is held at a High or Low logic level. If LEAB is Low, the A-bus data is stored in the latch/flip-flop on the Low-to-High transition of CPAB. When OEAB is Low, the outputs are active. When OEAB is High, the outputs are in the high-impedance state. The clocks can be controlled with the clock-enable inputs (CEBA/CEAB).

Data flow for B-to-A is similar to that of A-to-B but uses $\overline{\text{OEBA}},$ LEBA and CPBA.

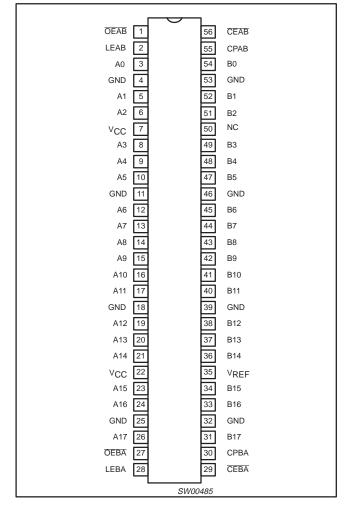
SYMBOL PARAMETER		CONDITIONS	TYPICAL	UNIT	
STWBOL	T _{amb} = 25° C		3.3 V	UNIT	
t _{PLH} t _{PHL}	Propagation delay An to Bn or Bn to An	C _L = 50 pF	1.9	ns	
C _{IN}	Input capacitance (Control pins)	$V_{I} = 0 V \text{ or } V_{CC}$	4	pF	
C _{I/O}	I/O pin capacitance	Outputs disabled; $V_{I/O} = 0 V \text{ or } V_{CC}$	8	pF	
I _{CCZ}	Total supply current	Outputs disabled	12	mA	

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DWG NUMBER
56-Pin Plastic TSSOP Type II	–40°C to +85°C	GTL16612 DGG	SOT364-1

GTL16612

PIN CONFIGURATION

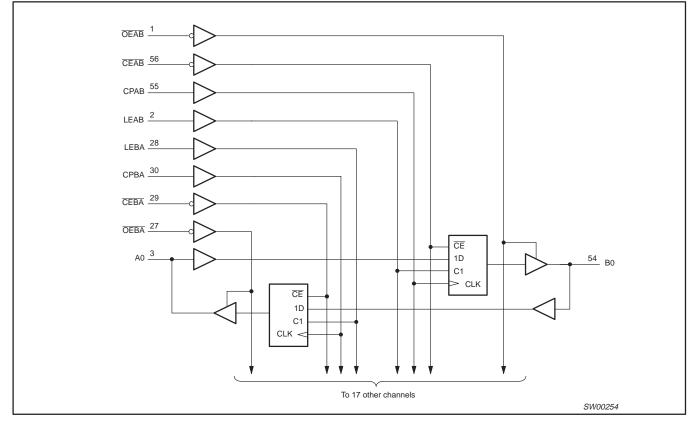


PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 27	OEAB/OEBA	A-to-B/ B-to-A Output enable input (active Low)
29, 56	CEBA/CEAB	B-to-A/A-to-B clock enable
2, 28	LEAB/LEBA	A-to-B/B-to-A Latch enable input
55,30	CPAB/CPBA	A-to-B/B-to-A Clock input (active rising edge)
3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26	A0-A17	Data inputs/outputs (A side)
54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31	B0-B17	Data inputs/outputs (B side)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0 V)
7, 22	V _{CC}	Positive supply voltage
35	V _{REF}	GTL reference voltage
50	NC	No connection

GTL16612

LOGIC SYMBOL (Positive Logic)



FUNCTION TABLE

	INPUTS							
CEAB ¹	OEAB ¹	LEAB ¹	CPAB ¹	Α	В			
Х	Н	Х	Х	Х	Z			
Х	L	Н	Х	L	L			
Х	L	Н	Х	Н	Н			
Н	L	L	Х	Х	₿ ₀ ²			
Н	L	L	Х	Х	B _O ²			
L	L	L	\uparrow	L	L			
L	L	L	\uparrow	Н	Н			
L	L	L	Н	Х	B _O ² B _O ³			
L	L	L	L	Х	B _O ³			

X = Don't care

H = High voltage level

L = Low voltage level

 \uparrow = Low to High

Z = High impedance "off" state

1. A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, CPBA, and CEBA.

2. Output level before the indicated steady-state input conditions were established.

3. Output level before the indicated steady-state input conditions were established, provided that CPAB was Low before LEAB went Low.

ABSOLUTE MAXIMUM RATINGS 1, 2

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V _I < 0	-50	mA
M	DC input voltogo ³	A port	-0.5 to +7.0	v
VI	DC input voltage ³	B port	-0.5 to +4.6	V
I _{OK}	DC output diode current	V _O < 0; A port	-50	mA
M		Output in Off or High state; A port	-0.5 to +7.0	V
Vo	DC output voltage ³	Output in Off or High state; B port	-0.5 to +4.6	V
		A port	128	mA
I _{OL}	Current into any output in the LOW state	B port	80	mA
I _{OH}	Current into any output in the HIGH state	A port	-64	mA
T _{stg}	Storage temperature range		-65 to +150	°C

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	TEST CONDITIONS	3.3 V RAN	3.3 V RANGE LIMITS		
STMBOL	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT	
V _{CC}	DC supply voltage		3.0	3.6	V	
M	Tampingting uplique	GTL	1.14	1.26	v	
V _{TT}	Termination voltage	GTL+	1.35	1.65	1 ×	
M		GTL	0.74	0.87	v	
V _{REF}	GTL reference voltage	GTL+	0.9	1.10	1 ×	
V		B port	0	V _{TT}	v	
VI	Input voltage	Except B port	0	5.5	1 [×]	
M		B port	V _{REF} +50 mV		v	
V _{IH}	HIGH-level input voltage	Except B port	2.0		1 [×]	
M		B port		V _{REF} –50 mV	v	
V _{IL}	LOW-level input voltage	Except A port		0.8	1 [×]	
I _{ОН}	HIGH-level output current	A port		-32	mA	
		B port		40	mA	
I _{OL}	LOW-level output current	A port		64		
T _{amb}	Operating free-air temperature range		-40	+85	°C	

GTL16612

DC ELECTRICAL CHARACTERISTICS (3.3 V ±0.3 V RANGE)

					LIMITS			
SYMBOL PARAMETER		METER	TEST CONDITIONS		Temp = -	UNIT		
					MIN	TYP ¹	MAX	
V _{IK}	Input clamp vo	ltage	V _{CC} = 3.0 V; I _{IK} = -18 mA			-0.85	-1.2	V
M	1 Park Lawred and		V_{CC} = 3.0 to 3.6 V; I_{OH} = -100 μ A	A	V _{CC} -0.2	V _{CC}		v
V _{OH}	High-level outp	out voltage	V _{CC} = 3.0 V; I _{OH} = -32 mA	A port	2.0	2.3		
			V _{CC} = 3.0 V; I _{OL} = 100 μA			0.07	0.2	
			V _{CC} = 3.0 V; I _{OL} = 16 mA	1		0.25	0.4	
V _{OL}	Low-level outp	out voltage	V _{CC} = 3.0 V; I _{OL} = 32 mA	A port		0.3	0.5	V
			V _{CC} = 3.0 V; I _{OL} = 64 mA	1		0.4	0.55	
			V _{CC} = 3.0 V; I _{OL} = 40 mA	B port		0.4	0.5	V
			V_{CC} = 3.6 V; V_{I} = V_{CC} or GND	Control size		0.1	±1	μA
			$V_{CC} = 0 \text{ or } 3.6 \text{ V}; \text{ V}_{I} = 5.5 \text{ V}$	Control pins		0.1	10	
			$V_{CC} = 3.6 \text{ V}; \text{ V}_{I} = 5.5 \text{ V}$	_		0.1	20	
ł	Input leakage curre	current	$V_{CC} = 3.6 \text{ V}; \text{ V}_{I} = V_{CC}$	I/O Data pins ⁴ A port		0.5	10	μA
		$V_{CC} = 3.6 \text{ V}; \text{ V}_{I} = 0$	1		0.1	-5		
			V_{CC} = 3.6 V; V_{I} = V_{TT} or GND	B port			±5	μΑ
I _{OFF}	Output off curre	ent	V_{CC} = 0 V; V _I or V _O = 0 to 4.5 V			0.1	±100	μΑ
h.e.e	Bus Hold curre		$V_{CC} = 3 \text{ V}; \text{ V}_{I} = 0.8 \text{ V}$			130		μA
HOLD	Bus Hold Curre	ent, A outputs	$V_{CC} = 3 \text{ V}; \text{ V}_{I} = 2.0 \text{ V}$			-140		μΑ
I_{EX}	Current into an High state whe		$V_{O} = 5.5 \text{ V}; V_{CC} = 3.0 \text{ V}$	A port		10	125	μΑ
I _{PU/PD}	Power up/down output current ³		$\frac{V_{CC} \leq 1.2 \text{ V}; \text{ V}_{O} = 0.5 \text{ V to } V_{CC}; \text{ V}}{\overline{OE} = \text{Don't care}}$	$V_{I} = GND \text{ or } V_{CC}$		1.0	±100	μA
I _{CCH}			Outputs high			5.0	9.0	
I _{CCL}	A-Port		Outputs low	1		10.5	18.5	1
I _{CCZ} 5		V _{CC} = 3.6 V	Disabled	$V_{I} = GND \text{ or } V_{CC}, I_{O} = 0$		6.0	11.5	mA
I _{CCH}	D. Dent		Outputs high]		9.7	17.5	
I _{CCL}	B-Port		Outputs low	1		7.0	12.0	
ΔI_{CC}	Additional supp input pin ²	oly current per	V_{CC} = 3 V to 3.6 V; One input at V Other inputs at V _{CC} or GND	/ _{CC} -0.6 V,		0.04	0.2	mA

NOTES:

All typical values are at V_{CC} = 3.3 V and T_{amb} = 25°C.
This is the increase in supply current for each LVTTL input at the specified voltage level other than V_{CC} or GND
This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 msec. From V_{CC} = 1.2 V to V_{CC} = 3.3 V ± 0.3 V a transition time of 100 µsec is permitted. This parameter is valid for T_{amb} = 25°C only.
Unused pins at V_{CC} or GND.

5. I_{CCZ} is measured with outputs pulled up to V_{CC} or pulled down to ground.

GTL16612

AC CHARACTERISTICS (A PORT)

GND = 0 V; t_r = t_f = 2.5 ns; C_L = 50 pF; R_L = 500 Ω ; T_{amb} = -40°C to +85°C.

			GTL			GTL+				
	GTL16612 An Po	rt	V _{CO}	V _{CC} = 3.3 V ±0.3 V			V _{CC} = 3.3 V ±0.3 V			
			,	V _{REF} = 0.8 \	/	,	V _{REF} = 1.0 \	/	UNIT	
SYMBOL	PARAMETER	WAVEFORM	MIN	TYP ¹	MAX	MIN	TYP ¹	MAX	1	
t _{PLH}	Bn to An	2	1.6	3.0	5.0	1.6	3.0	5.0	ns	
t _{PHL}	Bn to An	2	3.0	4.9	6.3	3.0	4.9	6.3	ns	
t _{PLH}	LEBA to An	3	1.6	2.7	4.2	1.6	2.7	4.2	ns	
t _{PHL}	LEBA to An	3	1.6	2.8	4.3	1.6	2.8	4.3	ns	
t _{PLH}	CPBA to An	1	1.9	3.4	4.7	1.9	3.4	4.7	ns	
t _{PHL}	CPBA to An	1	1.8	3.8	5.2	1.8	3.8	5.2	ns	
t _{PZH}	OEBA to An	5	1.5	2.6	4.2	1.5	2.6	4.2	ns	
t _{PHZ}	OEBA to An	5	1.4	2.9	4.8	1.4	2.9	4.8	ns	
t _{PZL}	OEBA to An	6	1.3	2.4	3.8	1.3	2.4	3.8	ns	
t _{PLZ}	OEBA to An	6	1.2	2.2	3.5	1.2	2.2	3.5	ns	

NOTE:

1. Typical values are at V_{CC} = 3.3 V, T_{amb} = +25°C.

AC CHARACTERISTICS (B PORT)

GND = 0 V; $t_r = t_f = 2.5 \text{ ns}$; $C_L = 30 \text{ pF}$; $R_L = 25 \Omega$; $T_{amb} = -40^{\circ}\text{C}$ to +85°C.

				GTL			GTL+		
	GTL16612 Bn Po	rt	V _{CO}	_c = 3.3 V ±0.	3 V	Vcc	; = 3.3 V ±0.	.3 V	1
				V _{REF} = 0.8 V			V _{REF} = 1.0 \	/	UNIT
SYMBOL	PARAMETER	WAVEFORM	MIN	TYP ¹	MAX	MIN	TYP ¹	MAX	
t _{PLH}	An to Bn	2	1.4	2.4	3.7	1.3	2.4	3.7	ns
t _{PHL}	An to Bn	2	1.3	2.5	4.0	1.4	2.6	4.2	ns
t _{PLH}	LEAB to Bn	3	1.7	3.0	4.4	1.8	3.0	4.6	ns
t _{PHL}	LEAB to Bn	3	2.1	3.5	5.4	2.3	3.6	5.5	ns
t _{PLH}	CPAB to Bn	1	1.8	3.1	4.5	1.9	3.1	4.8	ns
t _{PHL}	CPAB to Bn	1	2.3	3.6	5.4	2.4	3.8	5.8	ns
t _{PLH}	OEAB to Bn	7	1.1	2.1	3.3	1.4	2.0	3.5	ns
t _{PHL}	OEAB to Bn	7	1.6	2.8	4.4	1.0	2.9	4.5	ns

NOTE:

1. Typical values are at V_{CC} = 3.3 V, T_{amb} = +25°C.

GTL16612

AC SETUP REQUIREMENTS (3.3 V ±0.3 V RANGE)

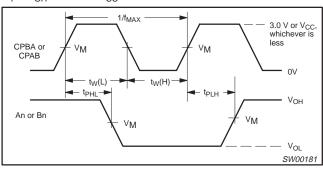
A Port: GND = 0 V; Input $t_r = t_f = 2.5 \text{ ns}$; $C_L = 50 \text{ pF}$; $R_L = 500 \Omega$; $T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$; $V_{REF} = 0.8 \text{ V or } 1.0 \text{ V}$. B Port: GND = 0 V; Input $t_r = t_f = 2.5 \text{ ns}$; $C_L = 30 \text{ pF}$; $R_L = 25 \Omega$; $V_{REF} = 0.8 \text{ V or } 1.0 \text{ V}$.

			LIN	UNIT	
SYMBOL	PARAMETER	WAVEFORM	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		
			MIN	MAX	1
t _s (H)	Setup time, High or Low	4	1.5		ns
t _s (L)	Bn to CPBA	4	1.5		ns
t _s (H)	Setup time, High or Low	4	2.0		ns
t _s (L)	An to CPAB	4	3.0		ns
t _h (H)	Hold time, High or Low	4	1.0		ns
t _h (L)	Bn to CPBA, or An to CPAB	4	1.0		ns
t _s (H)	Setup time, High or Low	4	1.0		ns
t _s (L)	Bn to LEBA, or An to LEAB	4	1.0		ns
t _h (H)	Hold time, High or Low	4	1.5		ns
t _h (L)	Bn to LEBA, or An to LEAB	4	1.5		ns
t _s (H)	Setup time, High or Low	4	1.0		ns
t _s (L)	CEAB to CPAB, or CEBA to CPBA	4	1.0		ns
t _h (H)	Hold time, High or Low	4	1.5		ns
t _h (L)	CEAB to CPAB, or CEBA to CPBA	4	1.0		ns
t _w (H)	Pulse width, High or Low	4	2.0		ns
t _w (L)	CPBA or CPAB	4	2.0		ns
t _w (H)	Pulse width, High LEBA or LEAB	3	1.5		ns

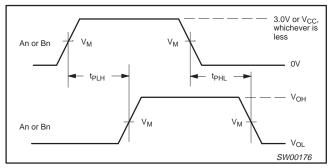
GTL16612

AC WAVEFORMS

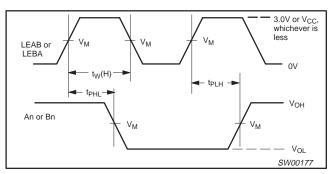
 $V_M = 1.5 \text{ V}$ at $V_{CC} \ge 3.0 \text{ V}$. $V_M = 1.5 \text{ V}$ for A ports and control pins; $V_M = 0.8 \text{ V}$ for B ports in GTL mode; $V_M = 1.0 \text{ V}$ for B ports in GTL+ mode. $V_X = V_{OL} + 0.3 \text{ V}$ at $V_{CC} \ge 3.0 \text{ V}$. $V_Y = V_{OH} - 0.3 \text{ V}$ at $V_{CC} \ge 3.0 \text{ V}$.



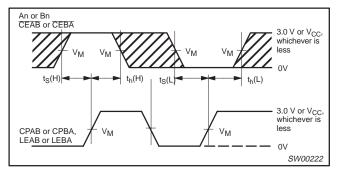
Waveform 1. Propagation delay, clock input to output, clock pulse width, and maximum clock frequency



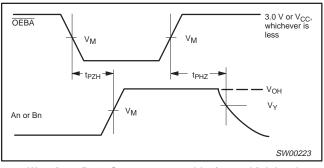
Waveform 2. Propagation delay, transparent mode



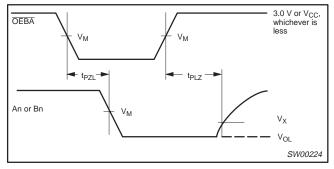
Waveform 3. Propagation delay, enable to output, and enable pulse width



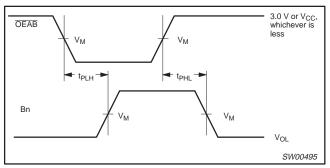
Waveform 4. Data setup and hold times



Waveform 5. 3-State output enable time to high level and output disable time from high level



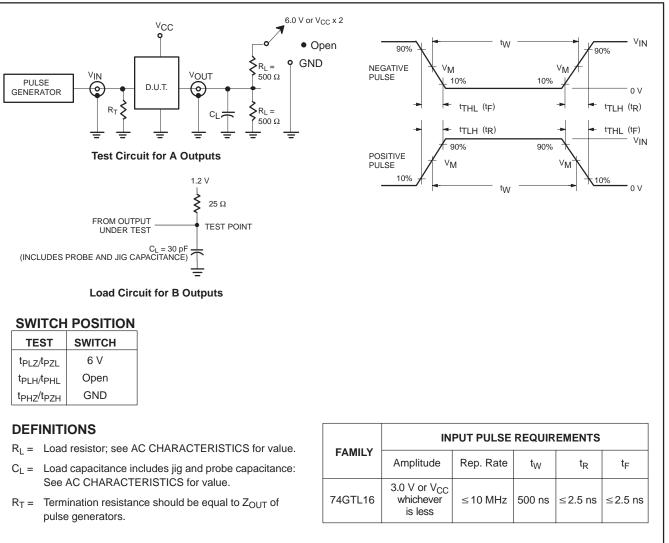
Waveform 6. 3-State output enable time to low level and output disable time from low level



Waveform 7. Output enable time on open collector output with pullup

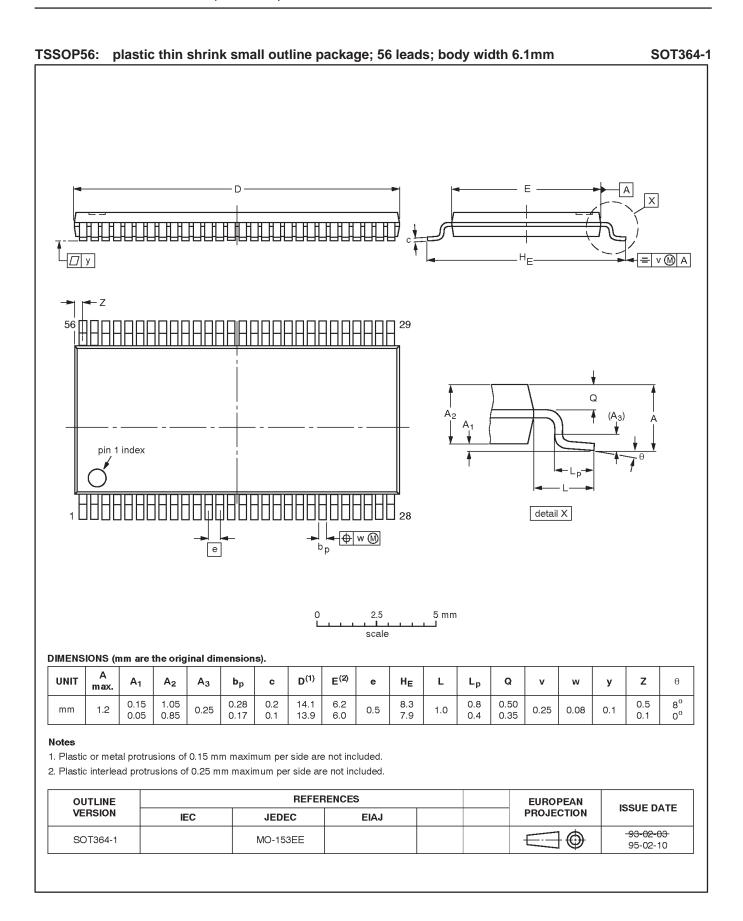
GTL16612

TEST CIRCUIT



SW00255

GTL16612



Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Disclaimers

Life support — These products are not designed for use in life support appliances, devices or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Philips Semiconductors 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088–3409 Telephone 800-234-7381 © Copyright Philips Electronics North America Corporation 2000 All rights reserved. Printed in U.S.A.

> Date of release: 06-00 9397-750 07217

Document order number:

he il : . . he ile c

Let's make things better.



